

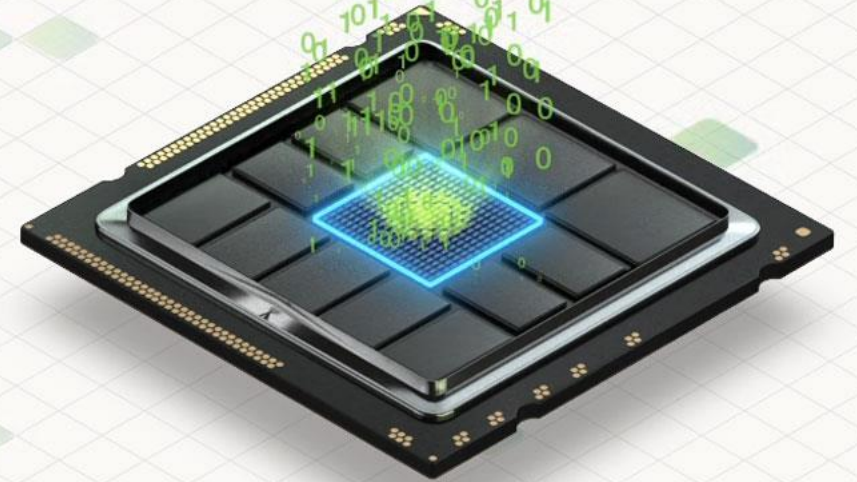
ReRAM: From Concept to Product

Amir Regev

Dec. 08, 2022

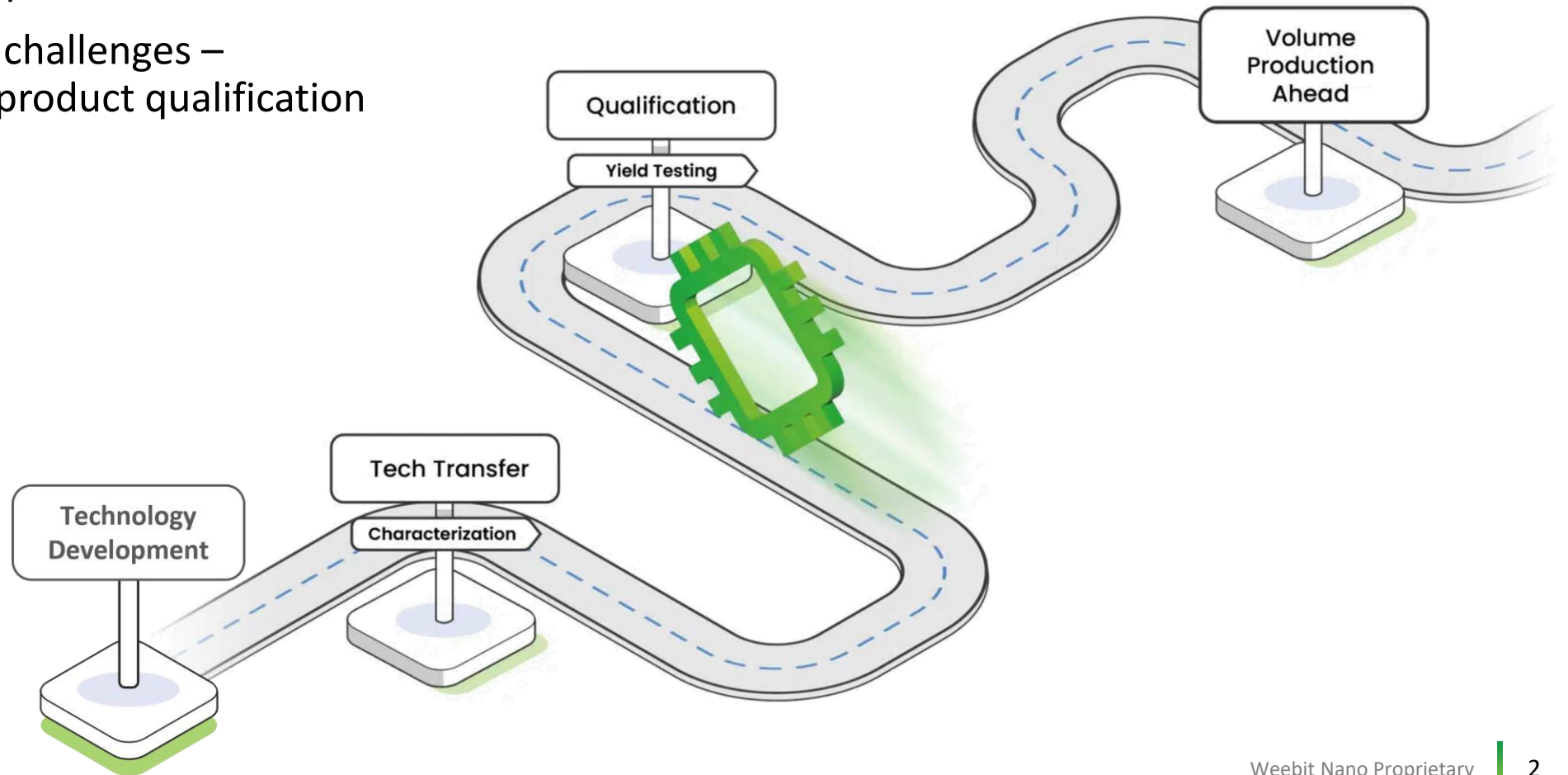


NVMTS 2022 select, redacted slides



Agenda

- ❖ Weebit Nano introduction
- ❖ ReRAM basic operation
- ❖ Lab-to-market challenges – Road towards product qualification
- ❖ Conclusions



Who We Are?

Leading developer of innovative next-generation memory technologies for the global semiconductor industry

We are enabling a leap forward in memory technology for a new era of connected devices



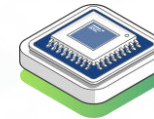
Founded: 2015

Located in Israel & France
ASX: WBT



R&D partner

CEA-Leti, leading micro-electronics research institute



Silicon-proven technology

Volume production expected 2023
Proven in production-fab wafers



World-leading team

50 personnel* (90% engineers/ scientists)



Signed 1st commercial deal

Ongoing discussions with additional fabs and customers



Technology status

1st memory module demonstration;
Successfully qualified IP module



Financial strength

Raised A\$35m in Nov.
2021 Well funded to 2024



Current business model

Product & IP licensing to semiconductor companies & fabs



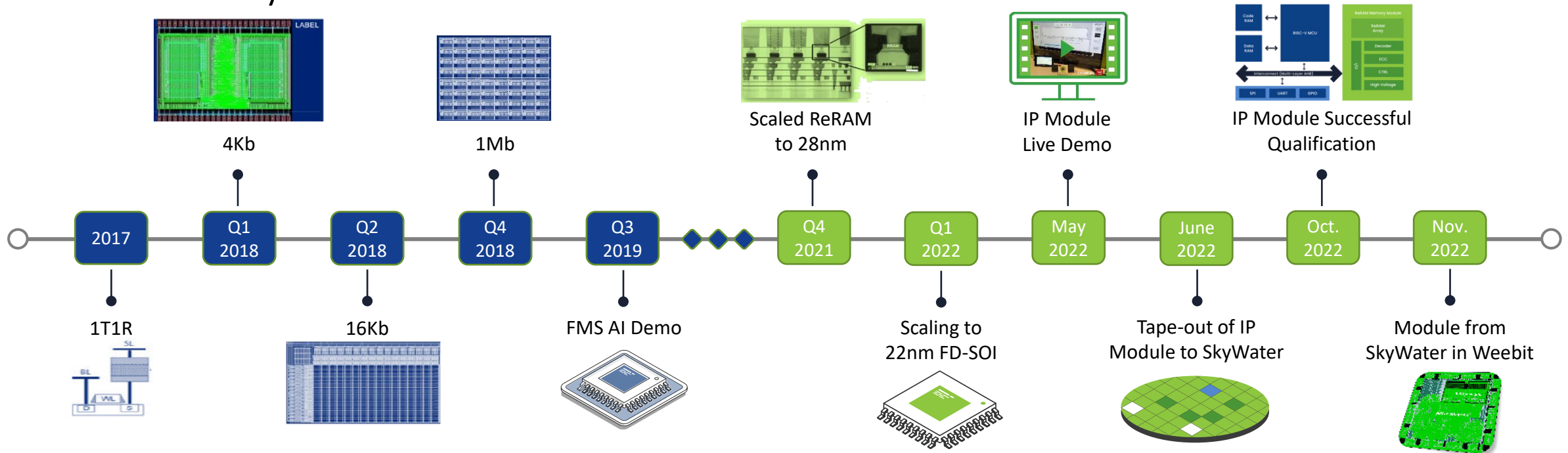
Process nodes

130nm, 28nm, 22nm under development
Bulk, FD-SOI, FinFET

* Includes employees and full-time contractors

Weebit-Leti Development Partnership

- ❖ Weebit is collaborating with CEA-Leti since 2016 to develop its ReRAM
 - ◆ Leveraging >10 years of ReRAM research at Leti
 - ◆ Weebit has full rights to all ReRAM-related IP
- ❖ The Weebit-Leti development collaboration is yielding exciting results:
 - ◆ Mbit arrays demonstrated at 28nm – 130nm



Cost Effective ReRAM NVM

❖ 2-mask adder

- ◆ Very few added steps

❖ Fab-friendly materials

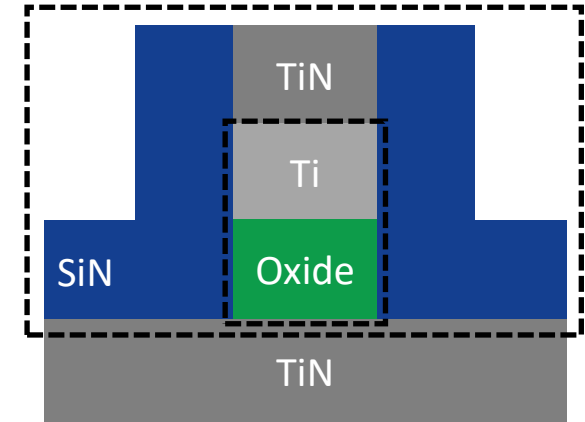
- ◆ No contamination risk, special handling, etc.

❖ Using existing deposition techniques and tools

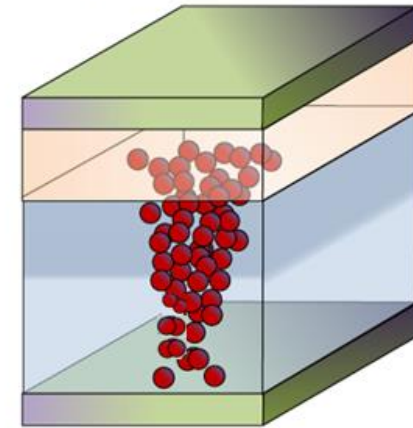
- ◆ Easy to integrate into any CMOS fab

❖ BEOL technology

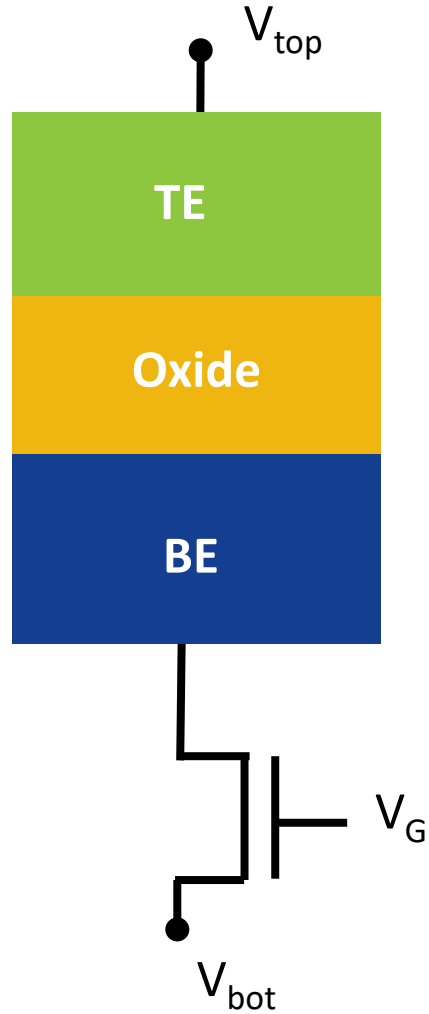
- ◆ Stack between any 2 metal layers
- ◆ No interference with FEOL
- ◆ Easy to scale from one process variation to another



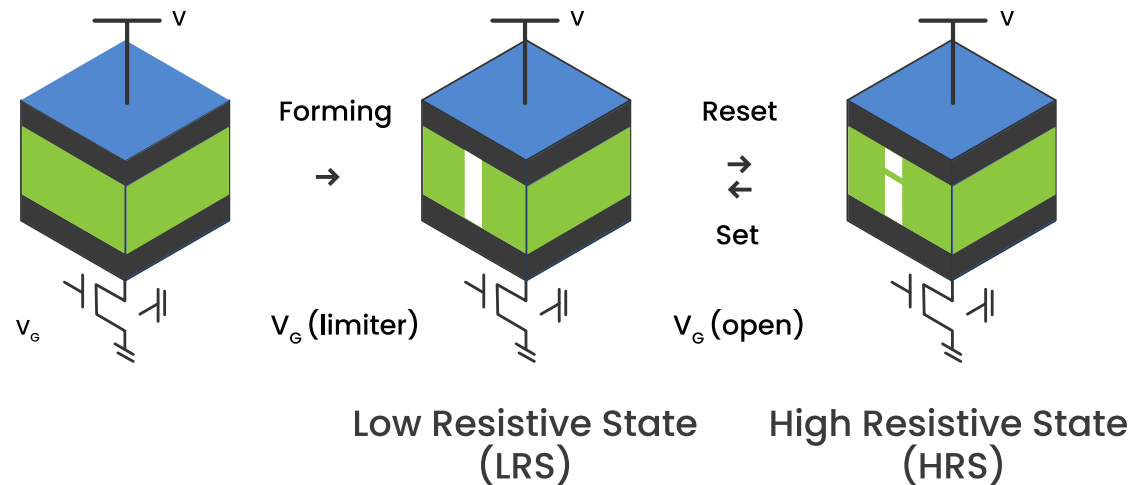
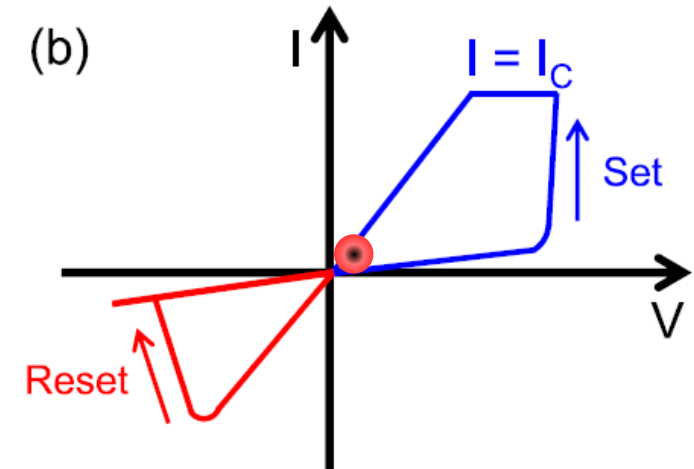
Oxygen Vacancy Filament



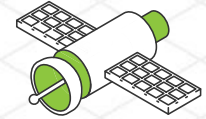
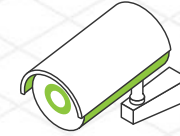
ReRAM Basic Operation



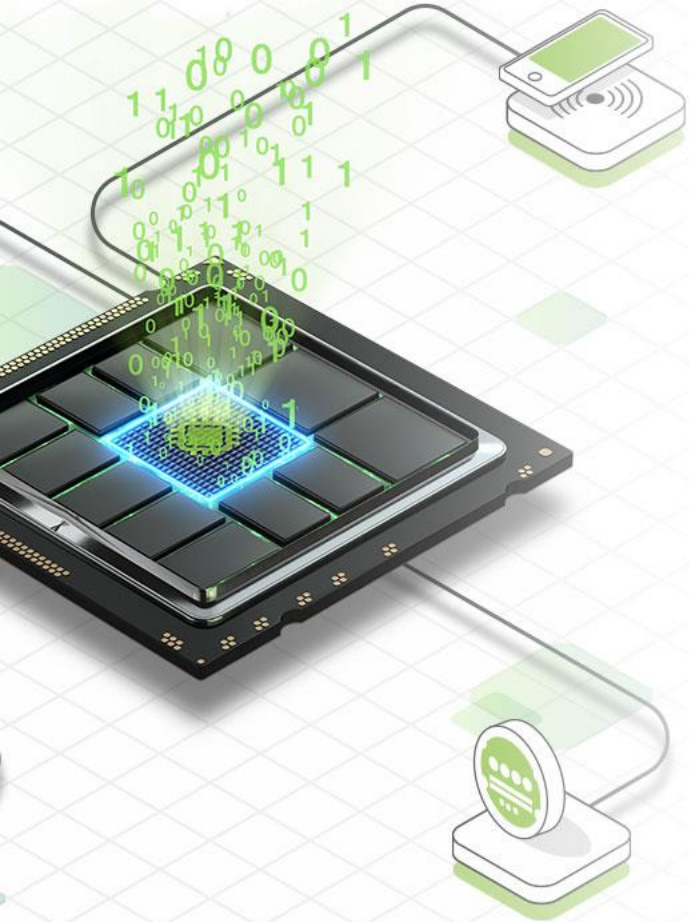
- ❖ SET (Program) – HRS → LRS
- ❖ RESET (Erase) – LRS → HRS



ReRAM Fits Various App Requirements



| | Mixed-Signal / Power Mgmt | IoT / MCUs | Edge AI | Automotive | Aerospace & Defense |
|---|------------------------------|------------|---------|------------|------------------------|
| Back-end-of-line tech for easy analog integration | ✓ | | | | |
| Cost-efficiency | ✓ | ✓ | ✓ | ✓ | |
| Ultra-low power consumption | ✓ | ✓ | ✓ | | |
| Robustness in high temp / extreme environments | ✓ | | | ✓ | ✓ |
| Scaling advantage at 28nm and below | | ✓ | ✓ | ✓ | |
| High Endurance | | ✓ | | ✓ | ✓ |
| Small footprint to store very large arrays | | | ✓ | ✓ | |
| Longevity | | ✓ | | ✓ | ✓ |
| Roadmap to neuromorphic computing | | | ✓ | | |

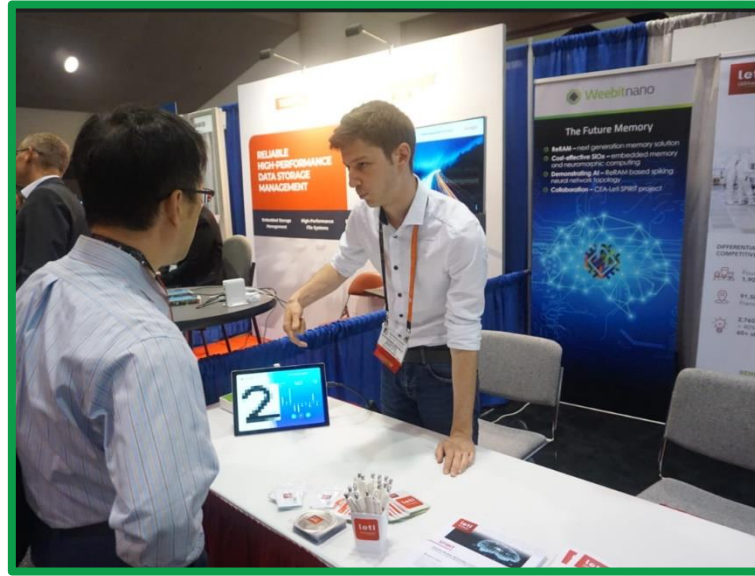


Making a Memory Product



Technology Demonstrations

SPIRIT Demo in *FMS 2019*

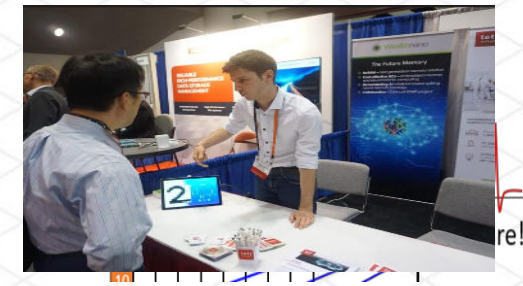
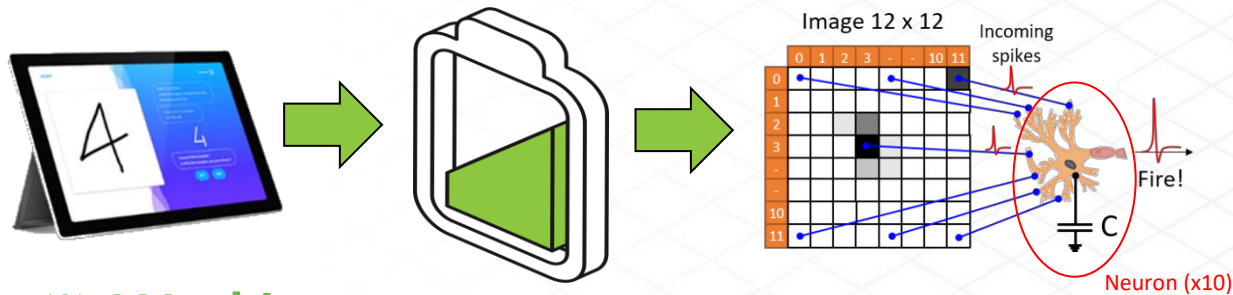


1st ever analog spiking neurons and ReRAM based synapses

Module Demo in *LID 2022*

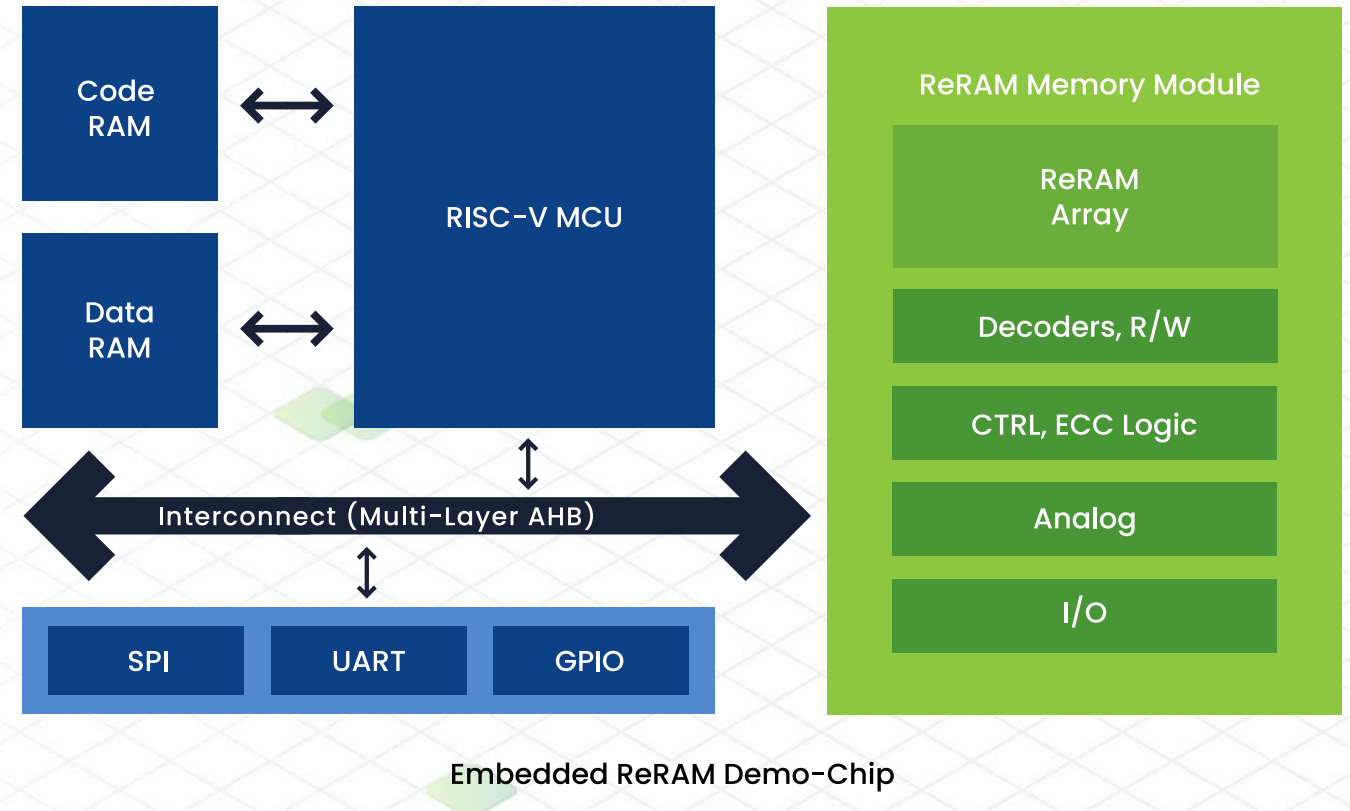


Embedded ReRAM with RISC-V processor

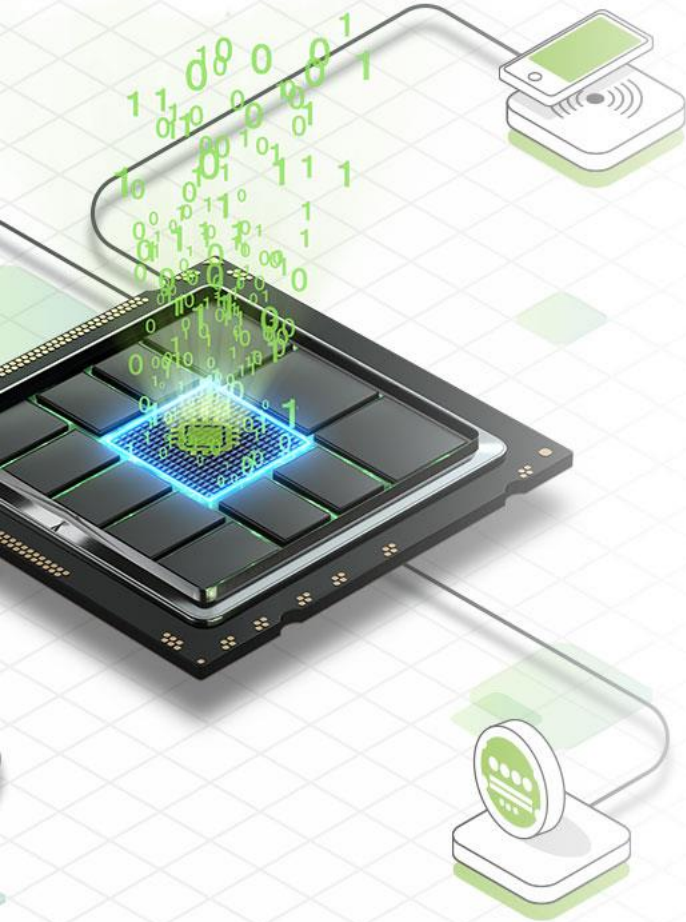


Weebit ReRAM Module Design in Qualification

- ❖ Integrating a ReRAM array in a complete module in 130nm technology
- ❖ The module includes
 - ◆ All analog circuitry
 - ◆ Smart algorithms (read, set/reset, forming)
 - ◆ Control logic and data manipulation
 - ◆ Redundancy, ECC
- ❖ The ReRAM module is further integrated into a complete subsystem based on a RISC-V processor
- ❖ Qualification concluded successfully



Module design is tightly coupled with Weebit's process & memory cell



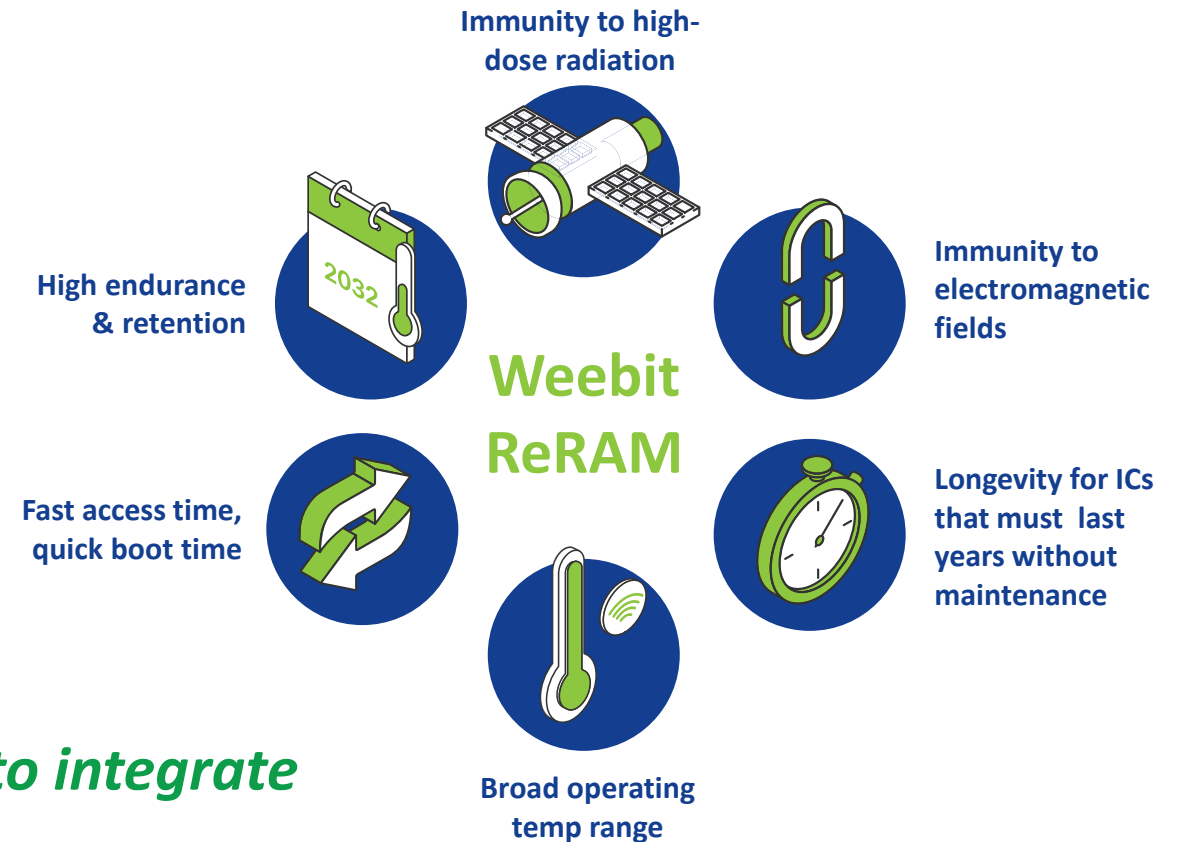
The Road from Design to Market



Technology Concept

- ❖ Every new technology starts with a concept
- ❖ Finding a promising materials set that demonstrates superior memory operation
- ❖ Performance should be groundbreaking – Advantages against the state-of-the-art
- ❖ Manufacturability – Not every material is fab-friendly or easy to integrate / process
- ❖ Cost effective solution – Should not include many added layers, special tooling or complicated process

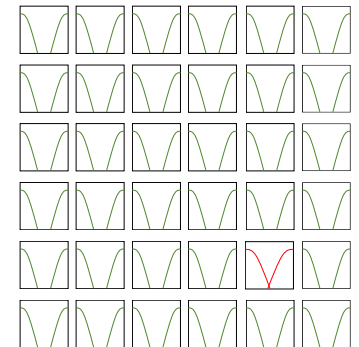
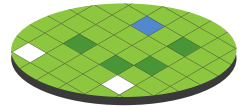
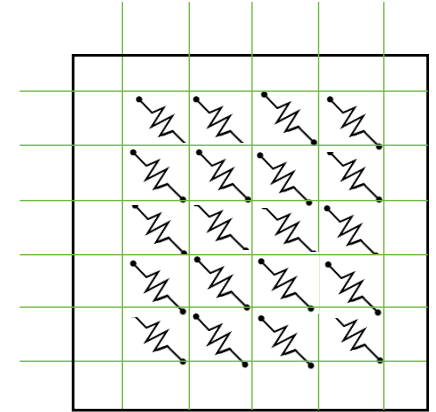
Technology needs to be *simple & easy to integrate*



Its All About Statistics

Each new technology starts with few single cells, BUT:

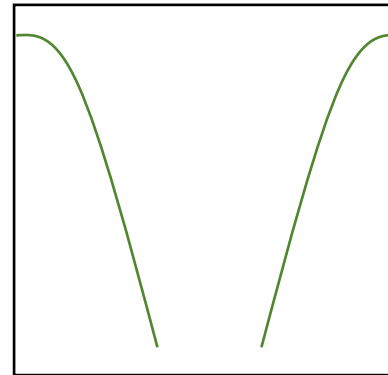
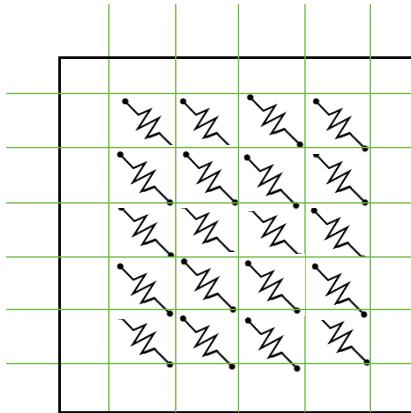
- ❖ How will they behave if we put a million of them together on the same chip?
 - ◆ What does their distribution look like?
 - ◆ How is their cell-to-cell variability? Does the distribution have tails?
 - ◆ Does the farthest cell get the same condition as the nearest cell?
- ❖ If we put millions of them on the same chip, how will they behave across an entire wafer?
 - ◆ What is their die-to-die variability? Is performance uniform?
 - ◆ What is the die yield (number of good dies per wafer)?
- ❖ What is the variance between different wafers and different production lots?
 - ◆ Does each lot have different results?
 - ◆ What is the lot-to-lot variability?
 - ◆ Is there any sensitivity to process variations?



From Analog to Digital

- ❖ In bit cell technology development, we look at analog value distributions
- ❖ Now we treat the values as data of zeros and ones, not just resistance values
- ❖ For a product to work, it needs to have no errors, otherwise data will be corrupted, or code will not execute correctly

Analog Resistance Values



Resistance



Code, or Data



Product Characterization & Qualification

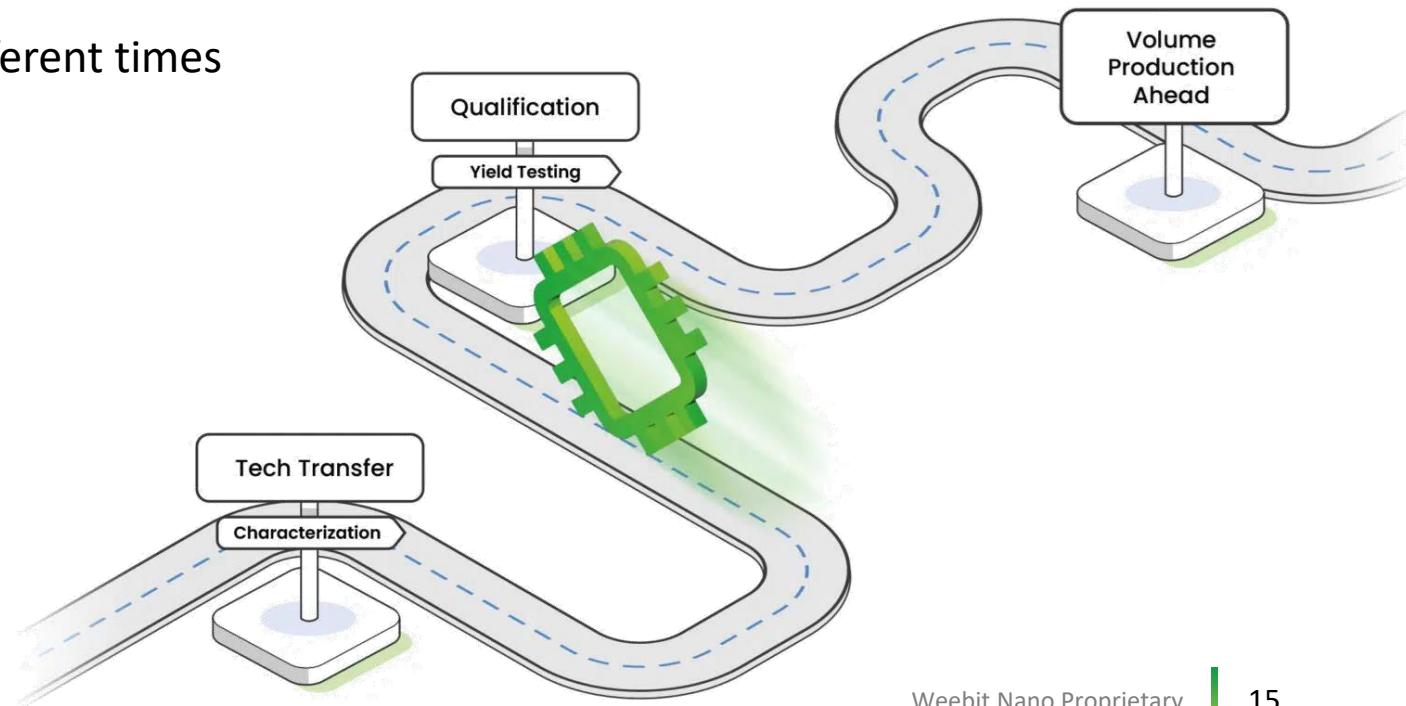
❖ Characterization

- ◆ Many conditions must be tested to determine performance to cover all operating conditions
 - Testing functionality at three temperatures – Cold (-40°C), Room and Hot (85 °C/125 °C/150 °C)
 - Testing at spec voltage range (Min, Type, Max)
 - Testing corner lot to create process variations (Fast, Typical, Slow)

❖ Qualification

- ◆ Testing three production lots samples at different times for the following:
 - Endurance
 - Retention
 - Read Disturb

*Characterization & qualification
can take some time*



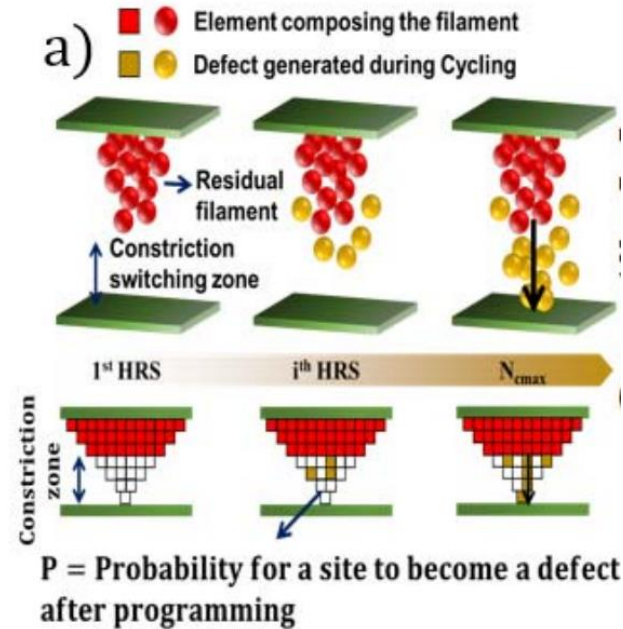
NVM Qualification Requirements

- ❖ Hundreds of dies, blindly selected from 3 independent production lots, must pass 100% of tests defined by JEDEC:

| Stress | Test Item | Reference | Stress Conditions | Test Conditions / Acceptance Criteria | Sample Size | Comments |
|--------|---------------------------|-------------------------|------------------------------|---------------------------------------|------------------|--------------------------|
| NVCE | Endurance | JESD22-A117 JEDEC 47 | Room and Hot | Datasheet Spec/ 0 Fails | 3 Lots/ 77 units | Test all the array bits |
| UCHTDR | Data Retention | JESD22-A117 JESD47 | Tstress – 125°C | 1000 hrs/ 0 Fail | 3 Lots/ 77 units | Readout at room and hot |
| PCHTDR | Post Cycle Data Retention | JESD22-A117 | Tstress = 125°C 100% spec | 10 hrs/ 0 Fail | 3 Lots/ 39 units | Readout at room and hot |
| SMT | SMT Reflow | ESD22 - A113 | Tc 260 °C | 3 cycles/ 0 fails | 3 Lots/ 25 units | Pb-Free Assembly Profile |

All Weebit ReRAM units passed all tests with zero failures

Non-Volatile Cycling Endurance (NVCE)

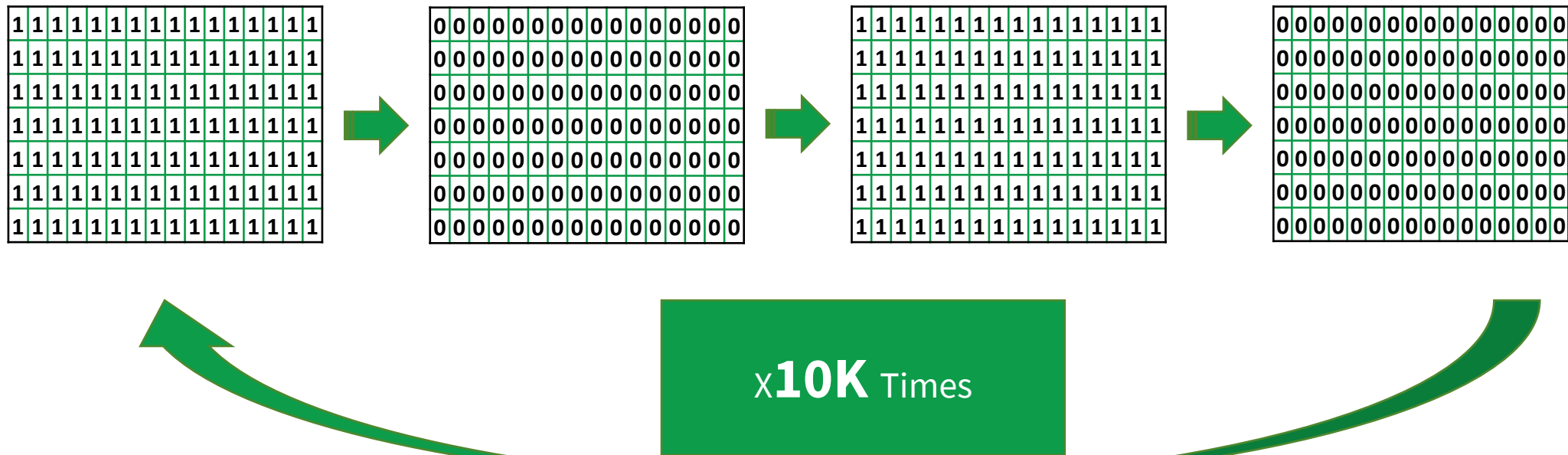


**D. Alfaro Robayo, IEEE TED 2019*

- ❖ Repetition of high stress during programming can lead to dielectric degradation due to defect generation
- ❖ After too many cycles, the dielectric can break leading to stuck LRS
- ❖ By smart algorithm we can reduce the stress and not break the filament

Non-Volatile Cycling Endurance (NVCE)

- ❖ For Program/Erase Endurance Cycling, a data change occurs when a stored “1” is changed to a “0”, or when a stored “0” is changed to a “1”
- ❖ Failure occurs when a write or erase data pattern within the memory array does not correspond to the intended data pattern



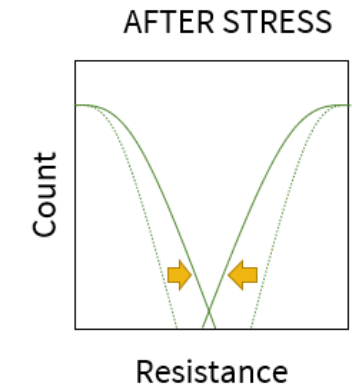
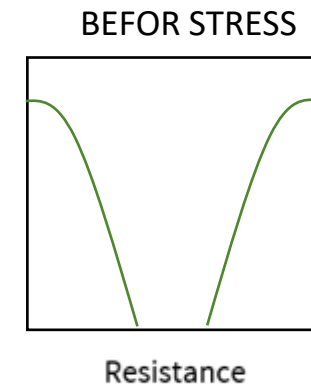
Data Retention

- ❖ Data retention is a measure of the ability of a memory cell in an NVM array to retain its charge state in the absence of applied external bias
- ❖ Data retention failure occurs when a memory cell no longer detected to be in its intended data state
- ❖ A bit flip is defined as the failure of a bit to retain its data state after a program or erase operation

| | | | | | | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |
| 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 |
| 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |
| 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 |
| 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |
| 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 |
| 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |



| | | | | | | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |
| 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 |
| 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |
| 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 |
| 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |
| 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 |
| 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |



Conclusions

- ❖ After several years of development, Weebit demonstrate a qualified technology at 130nm with good demonstration at 28nm
- ❖ Excellent data retention and endurance is demonstrated on our first embedded IP Module demo chip
- ❖ 1st module with Leti is fully qualified at hot temp while our 2nd module at SkyWater is now starting qualification



Thank You!

www.weebit-nano.com



 **Weebitnano**
THE NEXT NVM IS HERE